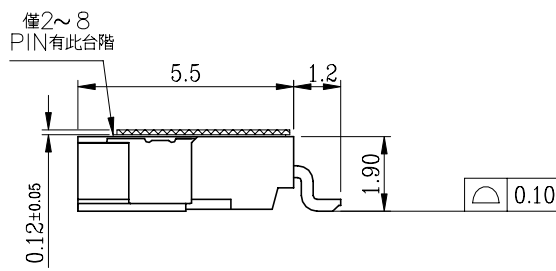
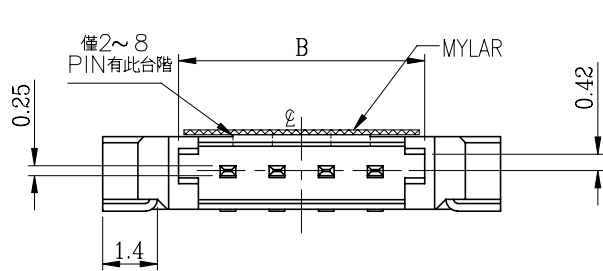


RECOMMENDED P.C. BOARD PATTERN DIM. (REF.)



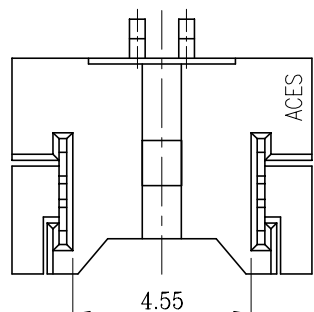
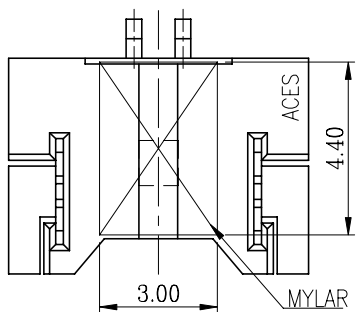
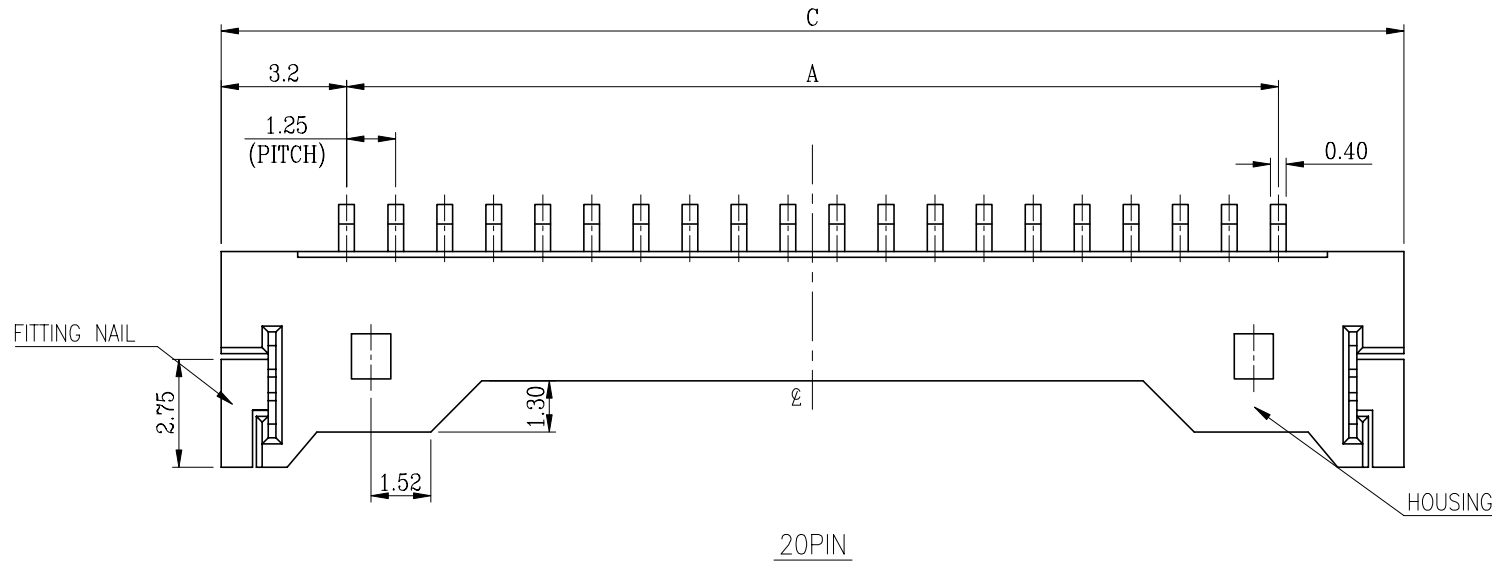
- NOTES:
- MATERIAL:
    - HOUSING: HALOGEN FREE PLASTIC,UL94V-0.
    - CONTACT: COPPER ALLOY
    - FITTING NAIL: COPPER ALLOY
  - FINISH:
    - CONTACT:
      - 50u"~100u" NICKEL UNDER PLATING OVER ALL GOLD FLASH ON CONTACT AREA
      - 50u"~100u" NICKEL UNDER PLATING OVER ALL 80u"~120u" PURE TIN ON CONTACT AREA
      - 50u"~100u" NICKEL UNDER PLATING OVER ALL 80u"~120u" MATT TIN ON CONTACT AREA
      - 50u"~100u" NICKEL UNDER PLATING OVER ALL 15u" MIN GOLD ON CONTACT AREA
      - 100u"~150u" NICKEL UNDER PLATING OVER ALL 15u" MIN GOLD ON CONTACT AREA
      - 100u"~150u" NICKEL UNDER PLATING OVER ALL 30u" MIN GOLD ON CONTACT AREA
      - 100u"~150u" NICKEL UNDER PLATING OVER ALL 10u" MIN GOLD ON CONTACT AREA
    - SOLDER:
      - 50u"~100u" NICKEL UNDER PLATING OVER ALL GOLD FLASH ON SOLDER AREA
      - 50u"~100u" NICKEL UNDER PLATING OVER ALL 80u"~120u" PURE TIN ON SOLDER AREA
      - 50u"~100u" NICKEL UNDER PLATING OVER ALL 80u"~120u" MATT TIN ON SOLDER AREA
      - 50u"~100u" NICKEL UNDER PLATING OVER ALL GOLD FLASH ON SOLDER AREA
      - 100u"~150u" NICKEL UNDER PLATING OVER ALL GOLD FLASH ON SOLDER AREA
      - 100u"~150u" NICKEL UNDER PLATING OVER ALL GOLD FLASH ON SOLDER AREA
      - 3u" GOLD ON CONTACT GOLD FLASH ON SOLDER AREA
    - FITTING NAIL:
      - 50u"~100u" NICKEL UNDER PLATING OVER ALL GOLD FLASH ON SOLDER TAILS
      - 50u"~100u" NICKEL UNDER PLATING OVER ALL 100u"~150u" PURE TIN ON SOLDER TAILS
      - 50u"~100u" NICKEL UNDER PLATING OVER ALL 100u"~150u" MATT TIN ON SOLDER TAILS
  - REFLOW SOLDER CAPABLE TO 260°C
  - PER ACES SPEC.
  - SPEC. PLS. REFER TO PS-50278-xxxx-xxx
  - PACKAGE PLS. REFER TO 88230-XX0X-TRP
  - PART NUMBER

P/N LEGEND	XXX	COLOR	PACKING
50278-XXX X X-XXX	001	BLACK	88230-XX0X-TRP
	002	NATURE	88230-XX0X-TRP
	003	BLACK	88230-XX0X-U-TRP

- PLATING
- L: PURE TIN
  - 1: GOLD FLASH
  - N: MATT TIN
  - C: CONTACT AREA:15u" GOLD PLATING SOLDER AREA: GOLD FLASH
  - W: CONTACT AREA:15u" GOLD PLATING SOLDER AREA: GOLD FLASH
  - D:30u" GOLD ON CONTACT(LEAD FREE) SOLDER AREA: GOLD FLASH
  - T:10u" GOLD ON CONTACT(LEAD FREE) SOLDER AREA: GOLD FLASH
  - A:3u" GOLD ON CONTACT(LEAD FREE) SOLDER AREA: GOLD FLASH
- PACKING
- O:TAPE&REEL(2~10PIN WITH MYLAR) (OTHER WITHOUT MYLAR)
  - 1:TUBE(2~10PIN WITH MYLAR) (OTHER WITHOUT MYLAR)
  - T:TAPE & REEL(WITHOUT MYLAR)
  - U:TUBE(WITHOUT MYLAR)

CKT.	DIM A	DIM B	DIM C	M/s(W)±0.10
2	1.25	3.77	7.65	3.00
3	2.50	5.02	8.90	3.00
4	3.75	6.27	10.15	6.00
5	5.00	7.52	11.40	6.00
6	6.25	8.77	12.65	6.00
7	7.50	10.02	13.90	10.00
8	8.75	11.27	15.15	10.00
9	10.00	12.52	16.40	10.00
10	11.25	13.77	17.65	12.00
11	12.50	15.02	18.90	X
12	13.75	16.27	20.15	X
14	16.25	18.77	22.65	X
15	17.50	20.02	23.90	X
16	18.75	21.27	25.15	X

<b>QUALITY SYMBOLS</b> MAJOR Ⓜ CRITICAL Ⓢ GENERAL TOLERANCES (UNLESS SPECIFIED) X: ±0.5 X: ±0.25 .XX: ±0.15 .XXX: ±0.1 ANGLES ±2°		DRAWN BY: TIANYINGHONG CHECKED BY: XUZHUYONG APPROVED BY: XUZHUYONG DATE: 21/05/18 DATE: 21/05/18 DATE: 21/05/18	<b>ACES ELECTRONICS</b> <b>1.25mm WIRE TO BOARD CONN.</b> <b>LPF-2 SMT R/A TYPE</b>
UNITS: mm SCALE: 1:1	 SHEET NO. 1 OF 2	SIZE: A4 REV: Q	RFG NO.: N/A DWG NO.: 50278-XXXXX-XXX



CKT.	DIM A	DIM B	DIM C	M/s(W)
20	23.75	26.27	30.15	X

<b>QUALITY SYMBOLS</b> MAJOR Ⓢ CRITICAL Ⓢ <b>GENERAL TOLERANCES (UNLESS SPECIFIED)</b> X ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	DRAWN BY TIANYINGHONG	DATE 21/05/18	
	CHECKED BY XUZHUYONG	DATE 21/05/18	
	APPROVED BY XUZHUYONG	DATE 21/05/18	<b>TITLE</b> 1.25mm WIRE TO BOARD CONN. LPF-2 SMT R/A TYPE
UNITS <b>mm</b>		SIZE <b>A4</b>	RFQ NO. <b>N/A</b>
SCALE <b>1:1</b>	SHEET NO. <b>2 OF 2</b>	REV <b>Q</b>	DWG NO. <b>50278-XXXXX-XXX</b>

单击下面可查看定价，库存，交付和生命周期等信息

[>>ACES\(宏致\)](#)